



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20150619003
Datasheet update for BQ25504
Information Only**

Date: 7/1/2015
To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this PCN are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

**20150619003
Information Only
Attachments**

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
BQ25504RGTT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20150619003	PCN Date:	07/01/2015
Title:	Datasheet update for BQ25504		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.

The product datasheet(s) is updated as seen in the change revision history below:



bq25504

SLUSAH0C – OCTOBER 2011 – REVISED JUNE 2015

www.ti.com

Changes from Revision B (December 2014) to Revision C

Page

• Changed the Test Condition for P _{IN(CS)} in the <i>Electrical Characteristics</i>	6
• Changed the values for P _{IN(CS)} in the <i>Electrical Characteristics</i> From: TYP = 10, MAX = 50 To: TYP = 15, MAX deleted	6
• Changed C _{FLTR} To: C _{BYP} Figure 14	18
• Changed CBYP = 0.1 µF To: CBYP = 0.01 µF in <i>Detailed Design Procedure</i>	18
• Changed C _{FLTR} To: C _{BYP} in Figure 21	21
• Changed CBYP = 0.1 µF To: CBYP = 0.01 µF in <i>Detailed Design Procedure</i>	21
• Changed C _{FLTR} To: C _{BYP} in Figure 28	23
• Changed CBYP = 0.1 µF To: CBYP = 0.01 µF in <i>Detailed Design Procedure</i>	23
• Changed Figure 34	26

The datasheet number will be changing.

Device Family	Change From:	Change To:
BQ25504	SLUSAH0B	SLUSAH0C

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/bq25504>

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

BQ25504RGTR	BQ25504RGTT
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com